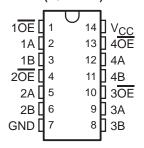
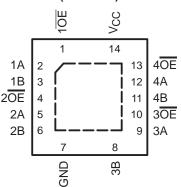
- **Undershoot Protection for Off-Isolation on** A and B Ports Up To -2 V
- **Bidirectional Data Flow, With Near-Zero Propagation Delay**
- Low ON-State Resistance (ron) Characteristics ($r_{on} = 3 \Omega$ Typical)
- **Low Input/Output Capacitance Minimizes Loading and Signal Distortion** $(C_{io(OFF)} = 5 pF Typical)$
- **Data and Control Inputs Provide Undershoot Clamp Diodes**
- **Low Power Consumption** $(I_{CC} = 3 \mu A Max)$
- V_{CC} Operating Range From 4 V to 5.5 V
- Data I/Os Support 0 to 5-V Signaling Levels (0.8-V, 1.2-V, 1.5-V, 1.8-V, 2.5-V, 3.3-V, 5-V)

- Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs
- Ioff Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Performance Tested Per JESD 22**
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)
- **Supports Both Digital and Analog** Applications: USB Interface, Bus Isolation, Low-Distortion Signal Gating

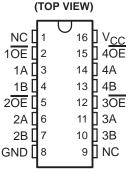
D, DB, DGV, OR PW PACKAGE (TOP VIEW)







DBQ PACKAGE



NC - No internal connection

description/ordering information

The SN74CBT3125C is a high-speed TTL-compatible FET bus switch with low ON-state resistance (r_{on}) , allowing for minimal propagation delay. Active Undershoot-Protection Circuitry on the A and B ports of the SN74CBT3125C provides protection for undershoot up to -2 V by sensing an undershoot event and ensuring that the switch remains in the proper OFF state.

The SN74CBT3125C is organized as four 1-bit bus switches with separate output-enable ($1\overline{OE}$, $2\overline{OE}$, $3\overline{OE}$, $4\overline{\text{OE}}$) inputs. It can be used as four 1-bit bus switches or as one 4-bit bus switch. When $\overline{\text{OE}}$ is low, the associated 1-bit bus switch is ON, and the A port is connected to the B port, allowing bidirectional data flow between ports. When OE is high, the associated 1-bit bus switch is OFF, and the high-impedance state exists between the A and B ports.

This device is fully specified for partial-power-down applications using Ioff. The Ioff feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.



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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

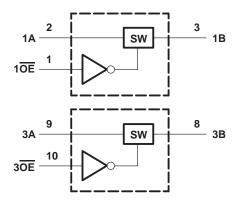
TA	PACKAGE	<u>=</u> †	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	QFN – RGY	Tape and reel	SN74CBT3125CRGYR	CU125C	
	0010 D	Tube	SN74CBT3125CD	00704050	
	SOIC - D	Tape and reel	SN74CBT3125CDR	CBT3125C	
	0000 00	Tube	SN74CBT3125CDB	014050	
-40°C to 85°C	SSOP – DB	Tape and reel	SN74CBT3125CDBR	CU125C	
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBT3125CDBQR	CU125C	
	TOOOD DW	Tube	SN74CBT3125CPW		
	TSSOP – PW	Tape and reel	SN74CBT3125CPWR	CU125C	
	TVSOP - DGV	Tape and reel	SN74CBT3125CDGVR	CU125C	

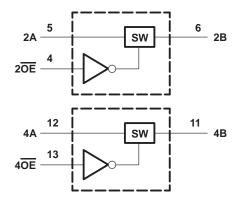
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each bus switch)

INPUT OE	INPUT/OUTPUT A	FUNCTION
L	В	A port = B port
Н	Z	Disconnect

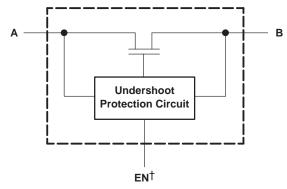
logic diagram (positive logic)





Pin numbers shown are for the D, DB, DGV, PW, and RGY packages.

simplified schematic, each FET switch (SW)



†EN is the internal enable signal applied to the switch.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	
Switch I/O voltage range, V _{I/O} (see Notes 1, 2, and 3)	
Control input clamp current, I_{IK} ($V_{IN} < 0$)	
I/O port clamp current, $I_{I/OK}$ ($V_{I/O}$ < 0)	
ON-state switch current, I _{I/O} (see Note 4)	
Continuous current through V _{CC} or GND terminals	±100 mA
Package thermal impedance, θ_{JA} (see Note 5): D package	86°C/W
(see Note 5): DB package	96°C/W
(see Note 5): DBQ package	90°C/W
(see Note 5): DGV package	127°C/W
(see Note 5): PW package	113°C/W
(see Note 6): RGY package	47°C/W
Storage temperature range, T _{stg}	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to ground unless otherwise specified.

- 2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 3. V_I and V_O are used to denote specific conditions for V_{I/O}.
- 4. II and IO are used to denote specific conditions for II/O.
- 5. The package thermal impedance is calculated in accordance with JESD 51-7.
- 6. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 7)

		MIN	MAX	UNIT
Vcc	Supply voltage	4	5.5	V
VIH	High-level control input voltage	2	5.5	V
VIL	Low-level control input voltage	0	8.0	V
V _{I/O}	Data input/output voltage	0	5.5	V
TA	Operating free-air temperature	-40	85	°C

NOTE 7: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN74CBT3125C QUADRUPLE FET BUS SWITCH 5-V BUS SWITCH WITH –2-V UNDERSHOOT PROTECTION

SCDS122A - JULY 2003 - REVISED OCTOBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAR	RAMETER		TEST CONDITIO	NS	MIN	TYP	MAX	UNIT
VIK	Control inputs	$V_{CC} = 4.5 \text{ V},$	$I_{IN} = -18 \text{ mA}$				-1.8	V
VIKU	Data inputs	V _{CC} = 5 V,	$0 \text{ mA} > I_{I} \ge -50 \text{ mA},$ $V_{IN} = V_{CC} \text{ or GND},$	Switch OFF			-2	V
I _{IN}	Control inputs	$V_{CC} = 5.5 \text{ V},$	$V_{IN} = V_{CC}$ or GND				±1	μΑ
loz‡		V _{CC} = 5.5 V,	$V_O = 0 \text{ to } 5.5 \text{ V},$ $V_I = 0,$	Switch OFF, V _{IN} = V _{CC} or GND			±10	μА
I _{off}		$V_{CC} = 0$,	$V_0 = 0 \text{ to } 5.5 \text{ V},$	V _I = 0			10	μΑ
ICC		V _{CC} = 5.5 V,	$I_{I/O} = 0,$ $V_{IN} = V_{CC} \text{ or GND},$	Switch ON or OFF			3	μА
∆lCC§	Control inputs	$V_{CC} = 5.5 \text{ V},$	One input at 3.4 V,	Other inputs at V _{CC} or GND			2.5	mA
C _{in}	Control inputs	$V_{IN} = 3 V \text{ or } 0$				3		pF
C _{io(OFF)}		$V_{I/O} = 3 \text{ V or } 0,$	Switch OFF,	$V_{IN} = V_{CC}$ or GND		5		pF
C _{io(ON)}		$V_{I/O} = 3 \text{ V or } 0,$	Switch ON,	$V_{IN} = V_{CC}$ or GND		12.5		pF
		$V_{CC} = 4 \text{ V},$ TYP at $V_{CC} = 4 \text{ V}$	V _I = 2.4 V,	I _O = -15 mA		8	12	
$r_{on}\P$			V 0	I _O = 64 mA		3	6	Ω
		V _{CC} = 4.5 V	V _I = 0	I _O = 30 mA		3	6	
			V _I = 2.4 V,	$I_O = -15 \text{ mA}$		5	10	

 $V_{\mbox{\footnotesize{IN}}}$ and $I_{\mbox{\footnotesize{IN}}}$ refer to control inputs. $V_{\mbox{\footnotesize{I}}},\,V_{\mbox{\footnotesize{O}}},\,I_{\mbox{\footnotesize{I}}},$ and $I_{\mbox{\footnotesize{O}}}$ refer to data pins.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	PARAMETER FROM (INPUT)		V _{CC} =	= 4 V	V _{CC} = 5 V ± 0.5 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	
tpd#	A or B	B or A		0.24		0.15	ns
t _{en}	ŌĒ	A or B		4.4	1.5	4	ns
^t dis	ŌĒ	A or B		4.4	1.5	4.4	ns

[#] The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).



[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] For I/O ports, the parameter IOZ includes the input leakage current.

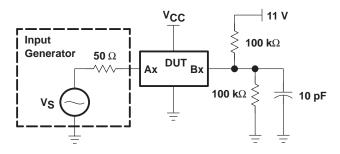
[§] This is the increase in supply current for each input that is at the specified voltage level, rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

undershoot characteristics (see Figures 1 and 2)

PARAMETER		TEST CONDI	MIN	TYP†	MAX	UNIT	
VOUTU	$V_{CC} = 5.5 \text{ V},$	Switch OFF,	$V_{IN} = V_{CC}$ or GND	2	V _{OH} -0.3		V

 $[\]dagger$ All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.





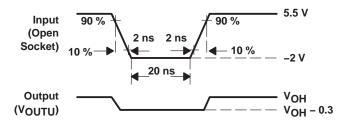
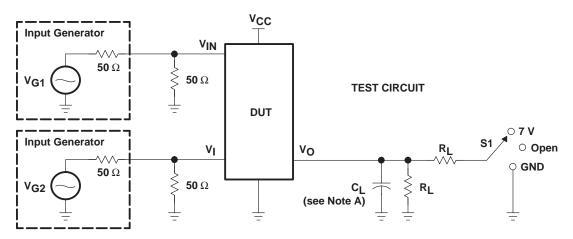
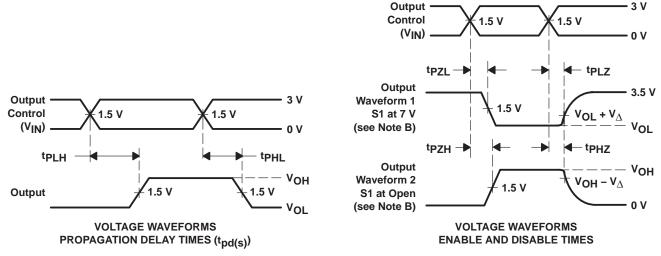


Figure 2. Transient Input Voltage (V_I) and Output Voltage (V_{OUTU}) Waveforms (Switch OFF)

PARAMETER MEASUREMENT INFORMATION



TEST	VCC	S1	RL	VI	CL	$v_{\!\scriptscriptstyle\Delta}$
^t pd(s)	$\begin{array}{c} \textbf{5 V} \pm \textbf{0.5 V} \\ \textbf{4 V} \end{array}$	Open Open	500 Ω 500 Ω	V _{CC} or GND	50 pF 50 pF	
tPLZ/tPZL	5 V ± 0.5 V 4 V	7 V 7 V	500 Ω 500 Ω	GND GND	50 pF 50 pF	0.3 V 0.3 V
tPHZ/tPZH	5 V ± 0.5 V 4 V	Open Open	500 Ω 500 Ω	V _{CC}	50 pF 50 pF	0.3 V 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as $t_{pd(s)}$. The tpd propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
- H. All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
	(.,	(=)			(0)	(4)	(5)		(5)
SN74CBT3125CD	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3125C
SN74CBT3125CD.B	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3125C
SN74CBT3125CDBQR	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU125C
SN74CBT3125CDBQR.B	Active	Production	SSOP (DBQ) 16	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU125C
SN74CBT3125CDBR	Active	Production	SSOP (DB) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CDBR.B	Active	Production	SSOP (DB) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CDBRG4	Active	Production	SSOP (DB) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CDBRG4.B	Active	Production	SSOP (DB) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CDE4	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3125C
SN74CBT3125CDR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3125C
SN74CBT3125CDR.B	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT3125C
SN74CBT3125CPW	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CPW.B	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CPWG4	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CPWG4.B	Active	Production	TSSOP (PW) 14	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CPWR	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CPWR.B	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CPWRE4	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CPWRG4	Active	Production	TSSOP (PW) 14	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CU125C
SN74CBT3125CRGYR	Active	Production	VQFN (RGY) 14	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU125C
SN74CBT3125CRGYR.B	Active	Production	VQFN (RGY) 14	3000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	CU125C

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.



PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2025

(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT3125CDBQR	SSOP	DBQ	16	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1
SN74CBT3125CDBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74CBT3125CDBRG4	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74CBT3125CDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74CBT3125CPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74CBT3125CRGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT3125CDBQR	SSOP	DBQ	16	2500	353.0	353.0	32.0
SN74CBT3125CDBR	SSOP	DB	14	2000	353.0	353.0	32.0
SN74CBT3125CDBRG4	SSOP	DB	14	2000	353.0	353.0	32.0
SN74CBT3125CDR	SOIC	D	14	2500	353.0	353.0	32.0
SN74CBT3125CPWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74CBT3125CRGYR	VQFN	RGY	14	3000	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74CBT3125CD	D	SOIC	14	50	507	8	3940	4.32
SN74CBT3125CD.B	D	SOIC	14	50	507	8	3940	4.32
SN74CBT3125CDE4	D	SOIC	14	50	507	8	3940	4.32
SN74CBT3125CPW	PW	TSSOP	14	90	530	10.2	3600	3.5
SN74CBT3125CPW.B	PW	TSSOP	14	90	530	10.2	3600	3.5
SN74CBT3125CPWG4	PW	TSSOP	14	90	530	10.2	3600	3.5
SN74CBT3125CPWG4.B	PW	TSSOP	14	90	530	10.2	3600	3.5

3.5 x 3.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



INSTRUMENTS www.ti.com



PLASTIC QUAD FLATPACK - NO LEAD



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
 The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



PLASTIC QUAD FLATPACK - NO LEAD



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.





SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.







NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
 4. Reference JEDEC registration MO-150.





NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.





SHRINK SMALL-OUTLINE PACKAGE



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 inch, per side.
- 4. This dimension does not include interlead flash.5. Reference JEDEC registration MO-137, variation AB.



SHRINK SMALL-OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SHRINK SMALL-OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.







NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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